

09-06-05

IFW 1765

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

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| SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT | | Docket Number 10191/2262 | |
| Application Number 10/070,286 | Filing Date July 8, 2002 | Examiner Anita Karen Alanko | Art Unit 1765 |
| Title METHOD FOR PRODUCING A SEMICONDUCTOR COMPONENT AND A SEMICONDUCTOR COMPONENT PRODUCED ACCORDING TO THE METHOD | | Applicant(s) Hubert BENZEL et al. | |

Address to:
Mail Stop PCT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

1. In accordance with the duty of disclosure under 37 C.F.R. § 1.56 and in conformance with the procedures of 37 C.F.R. §§ 1.97 and 1.98 and M.P.E.P. § 609, attorneys for Applicants hereby bring the following references (cited during prosecution of the corresponding German patent application) to the attention of the Examiner. The references are listed on the attached modified PTO Form No. 1449.

This Supplemental Information Disclosure Statement is being filed pursuant to 37 C.F.R. § 1.97(i), which provides that an Information Disclosure Statement that is filed before the grant of a patent but that does not otherwise comply with 37 C.F.R. § 1.97 and § 1.98 will be placed in the file, but not be considered by the Office.

2. To the extent that the reference is considered, the Commissioner is hereby authorized to charge payment of any appropriate fees that may be required to the deposit amount of **Kenyon & Kenyon**, deposit account number **11-0600**. A duplicate of this sheet is enclosed.
3. A copy of each patent, publication or other information listed on the modified PTO form 1449 is enclosed unless otherwise stated.

Dated: 9/1/2005By: Richard L. Mayer

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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT
PTO-1449**

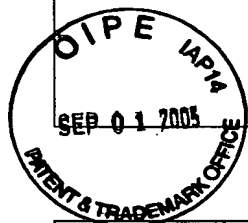
DOCKET NO.
10191/2262

SERIAL NO.
10/070,286

APPLICANT
Hubert BENZEL et al.

FILING DATE
July 8, 2002

GROUP
1765



U. S. PATENT DOCUMENTS

| EXAMINER INITIAL | PATENT/PUBLICATION NUMBER | PATENT/PUBLICATION DATE | NAME | CLASS | SUBCLASS | FILING DATE |
|---------------------|------------------------------|----------------------------|------|-------|----------|----------------|
| | 5,674,406* | October 7, 1997 | Lee | | | |
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* Copy of reference is not enclosed pursuant to Official Gazette Notice dated August 5, 2003.

FOREIGN PATENT DOCUMENTS

| EXAMINER INITIAL | DOCUMENT NUMBER | DATE | COUNTRY | CLASS | SUBCLASS | TRANSLATION | |
|---------------------|--------------------|--------------------|---------|-------|----------|-------------|----|
| | | | | | | Yes | No |
| | 19803013 | August 5, 1999 | DE | | | X* | |
| | 4202455 | August 19, 1993 | DE | | | X* | |
| | 99/45583 | September 10, 1999 | WO | | | | |
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** English language abstract provided.

OTHER DOCUMENTS

| EXAMINER INITIAL | AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC. |
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| | Jun-Hwan Sim et al., "Eight-beam piezoresistive accelerometer fabricated by using a selective porous-silicon etching method", pp. 273-8, Sensors and Actuators A66 (1988). |
| | Walter Lange et al., Sensors and Materials, Vol. 8, no. 6, "Porous Silicon Technology for Thermal Sensors", pp. 327-44 (1986). |
| | Rosemary L. Smith, "Electrochemical Microfabrication", The Electrochemical Society Proceedings, Proc. Vol. 94-32, Miami Beach Conf., 10-12.10.1994, pp. 281-289 (1995). |
| | V. Labunov et al., "Heat Treatment Effect on Porous Silicon", Vol. 137, pp. 123-134, Thin Solid Films, 1.3. (1986) |

| EXAMINER | DATE CONSIDERED |
|---|-----------------|
| EXAMINER: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. | |